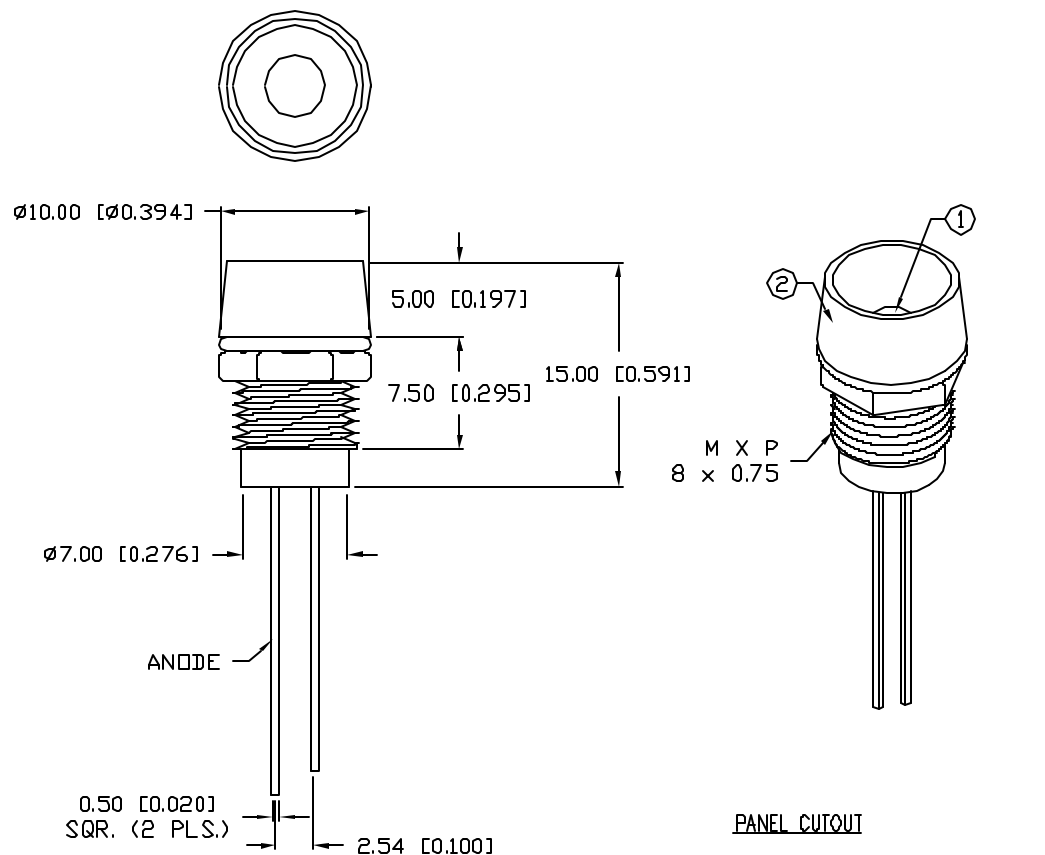


UNCONTROLLED DOCUMENT

PART NUMBER
SSI-LXR4815YD

REV.
C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	UPDATED SAFE OPER. SPECS.	10.27.94
B	E.C.N. #10674.	10.30.00
C	E.C.N. #10BRDR. & REDRAWN IN 3D.	11.15.01



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		2.1	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		20		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		60		$2x$ theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	YELLOW DIFFUSED				

NOTES:

1. SSL-LX5063YD, YELLOW LED.
2. SSI-LXR4815, CHROME HOUSING.
3. SSH-LXH4815BSG, BLACK NYLON BUSHING. (NOT SHOWN).
4. INSERT LED LEADS INTO BUSHING, THEN INSERT INTO HOUSING. CRIMP BUSHING INTO PLACE.

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	$\text{mW}/^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX
* $t < 10\mu\text{s}$		

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= ± 1 (± 0.039), XX= ± 0.5 (± 0.020), XXX= ± 0.25 (± 0.010), XXXX= ± 0.127 (± 0.005). LEAD SIZE= ± 0.05 (± 0.002), LEAD LENGTH= ± 0.75 (± 0.030), MIN= $\frac{+0.00}{-0.00}$ DECIMAL PRECISION MAX= $\frac{+0.00}{-0.00}$ DECIMAL PRECISION

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T-5mm 585nm YELLOW LED PANEL INDICATOR,
YELLOW DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 10.2.90
			PAGE: 1 OF 1
			SCALE: N/A